

# Notes

No tracks or vias in the shaded keepout area.

No other track or signal within 0.020" of any contact pad.

Do not allow solder paste on the contact pads. It is essential to eliminate any hole in the solder paste-mask (solder stencil) layer. If this is not possible make the contact pads thru-hole with finished hole size of 0.008" or less.

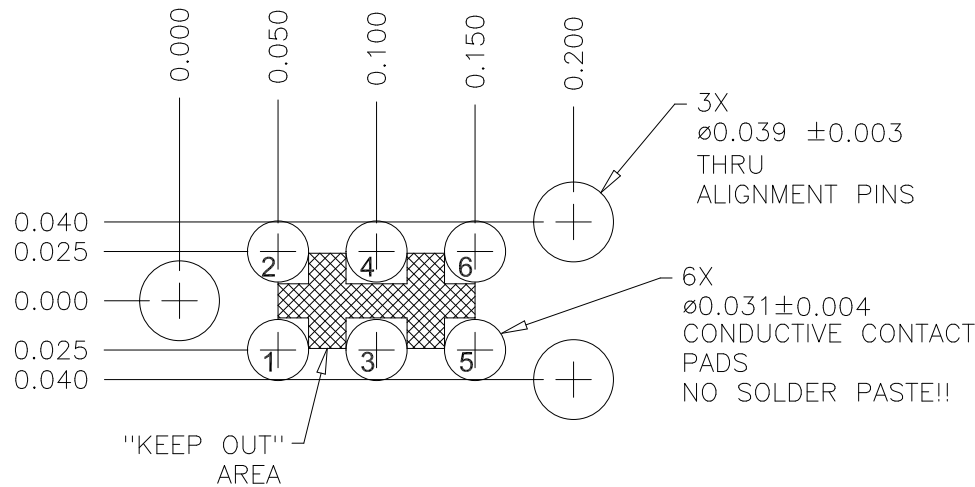
To avoid ordering confusion, please specify DNL in your BOM.

REVISIONS		
#	DESCRIPTION	DATE

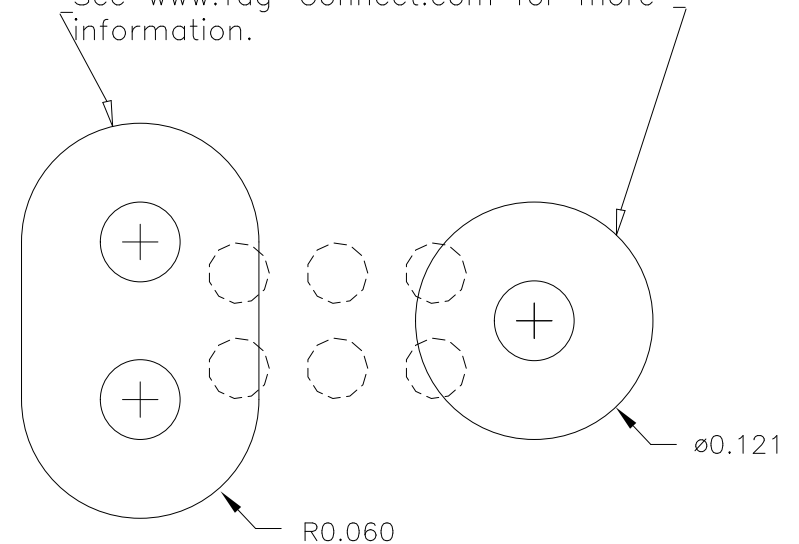
Optional copper pads allow soldering of s/steel alignment pins to underside of board for debugging use. Use stainless steel soldering flux and care to avoid melting the connector.

Alternatives include the TC2030-CLIP board that grips the s/steel pins from the underside or Mill-Max receptacles P/N 0295-0-15-XX-06-XX-10-0

See [www.Tag-Connect.com](http://www.Tag-Connect.com) for more information.



**PCB TOP LAYER**



**OPTIONAL BOTTOM LAYER  
ALTERNATIVE - USE TC2030-CLIP BOARD**

Microchip ICD/ICSP Signals

- Pin 1: -MCLR/Vpp
- Pin 2: Vdd
- Pin 3: Ground
- Pin 4: PGD (ICSPDAT)
- Pin 5: PGC (ICSPCLK)
- Pin 6: Unused or LVP

[www.TAG-CONNECT.com](http://www.TAG-CONNECT.com)

TITLE  
TC2030-MCP-NL-FP  
FOOTPRINT FOR TC2030-MCP-NL

UNLESS OTHERWISE NOTED  
DIMENSIONS ARE IN INCHES

.XXX±	.XX±	ANGLE ±
.005	.01	1.5°

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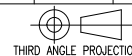
SCALE: 10:1

DRAWN  
PM / NS

DATE  
4/5/10

CHECKED

DATE



SIZE  
A SHEET 1 OF 1

DWG. NO.

REV.  
D

CUSTOMER:

FILE: